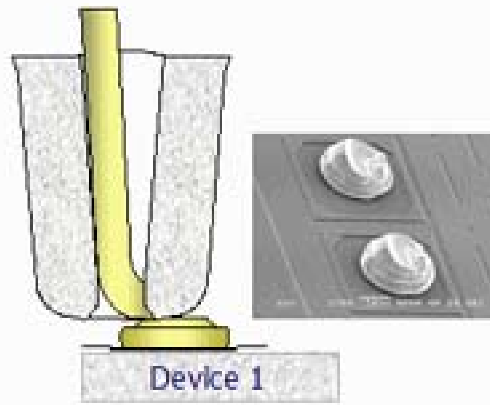
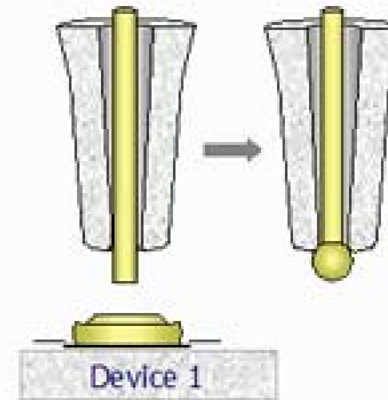
BSOB Bonding Sequence

Step 1: Ball bond formation on Device 1



Step 2: Tearing of the wire

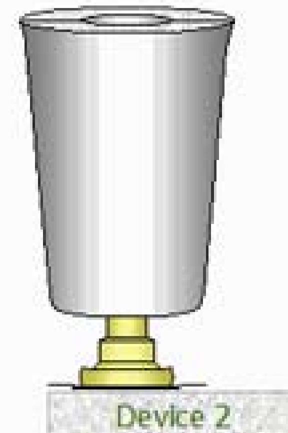
Note: Programmable sequence is used to flatten the bond before the tearing action



Step 3: Capillary rises for next free air ball formation

Step 5: Stitch bond formation on top of bump on Device 2

Note: The capillary is offset to ensure the stitch is on the flat of the bump



Step 4: Ball bond formation on Device 2

SPT small precision tools